



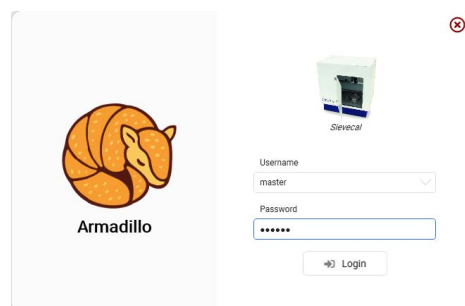
# Sievecal

FULLY AUTOMATIC LABORATORY TEST SIEVE  
CALIBRATION APPLICATION USING  
IMAGING TECHNOLOGY

CLICK GRAPHICS FOR VIDEO



**COMPLETE PRODUCT VIDEO  
ORIGINAL CALLISTO SOFTWARE**



**NEW ARMADILLO SOFTWARE**

**ABSOLUTE STABILITY WITH  
MEASUREMENTS**

**CAN BE USED WITH  
ELECTROFORMED SIEVES**

**AI POWERED TECHNOLOGY  
AUTOMATICALLY REMOVES  
CLOGGED APERTURES FROM  
ANALYSIS**

**CAN BE USED FOR PARTICLE SIZING  
APPLICATIONS**



# Sievecal

Is a fully automated instrument designed to provide pass fail compliance data for laboratory test sieves



## How it works

With an average analysis time of two minutes, (inspection grade) sieves are quickly and accurately verified for compliance to ASTM, DIN, or ISO Standards.

Using sophisticated digital imaging hardware, and robust software package, a pre-defined standard operating procedure makes testing sieves as easy as a click of a mouse.

As the sieve rotates, the entire surface of the mesh is analyzed, providing real time information on wire thickness, and aperture dimensions. A fully report is generated for each sieve, and can be printed, or saved as a file.



### Why chose Occhio Sievecal

- Fast sieve analysis, measures apertures as well as wire thickness
- 2 minutes pass fail SOP
- Comprehensive software package
- Complete report generation capabilities



### Key points

**Compatible** with 3inch, 8inch, 12inch, 100mm, 200mm, 300mm ASTM and ISO sieves formats

**Apertures from 38µm to 12mm**

**Fully computer controlled procedure** including autofocus

**Provides ASTM E 11-13 Pass Fail Criteria:**  
Min Sieve opening    Min wire diameter  
Min Std. Deviation    Max Std. Deviation  
Sieve Opening X (Mean Min Max Std. Dev.)  
Sieve Openin Y (Mean Min Max Std. Dev.)  
Wire Thickness X (Mean Min Max Std. Dev.)  
Wire Thickness Y (Mean Min Max Std. Dev.)

## Technical specifications



<b>Dimensions and weight</b>	<i>Width x Deep x Height</i> <i>Weight</i>	83 x 60 x 87 cm 57 kg
<b>Working conditions</b>	<i>Working temperature</i>  <i>Power Supply</i>	Temperature 5°C – 25°C Humidity 35% - 80% non-condensing 100-220 Vac 50-60Hz (external power supply module included with the packing)
<b>External computer</b> <i>(Optional - minimum specification)</i>	<i>Processor</i> <i>Ram</i> <i>Hard Disk</i> <i>Display</i> <i>Mouse, keyboard</i> <i>Operating system</i>	Intel Core i7 5820K@3.3GHz 32GB DDR4 2.133MHz 1 TB + SSD 256GB 1920 x 1080 usb, US Keyboard Windows 11 64 bits (or 10 Pro 64 bits)
<b>Optics and imaging device</b>	<i>Standard camera type</i>  <i>Camera resolution</i> <i>(Zoom front lens included)</i> <i>(Zoom front lens not included)</i> <i>Lens type</i> <i>Light source</i>	USB 3, ultra high resolution  from 2.5up to 14.9 μm/pixel from 0.7 up to 4.1 μm/pixel Telecentric zoom (from x4.5 up to x0.24) Monochrome 450nm blue light
<b>Instrument main features</b>	Sieve opening Sieve size supported Sieve opening computing  Dedicated acquisition and reporting software compliant with ASTM E11 standard Fully automated flat scanning table (sieve rotation and translation) Standard analysis duration approximately 2 minutes Easy focusing Non Contact inspection measure Detection and counting of clogged opening (relative proportion)	from 38μm to 12.5mm 3, 6 and 12 inch, sieve adaptor included X Opening, Y Opening X Wire Thickness, Y Wire Thickness

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## QUICK QUOTE